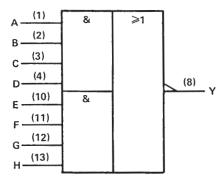
- Package Options Include "Small Outline" Packages, Ceramic Chip Carriers and Flat Packages, and Plastic and Ceramic DIPs
- Dependable Texas Instruments Quality and Reliability

description

These devices contain 2-wide 4-input AND-OR-INVERT gates. They perform the Boolean function $Y = \overline{ABCD + EFGH}$.

The SN54LS55 is characterized for operation over the full military temperature range of $-55\,^{\circ}\text{C}$ to 125 $^{\circ}\text{C}$. The SN74LS55 is characterized for operation from 0 $^{\circ}\text{C}$ to 70 $^{\circ}\text{C}$.

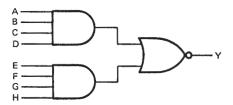
logic symbol†



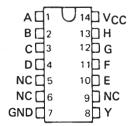
positive logic: $Y = \overline{ABCD + EFGH}$

Pin numbers shown are for D, J, N, and W packages.

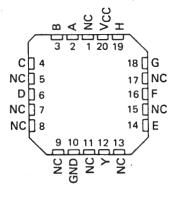
logic diagram



SN54LS55 . . . J OR W PACKAGE SN74LS55 . . . D OR N PACKAGE (TOP VIEW)

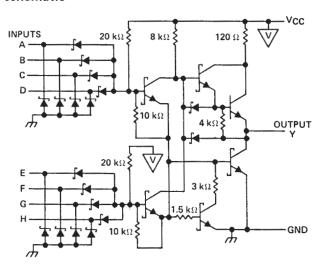


SN54LS55 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

schematic



Resistor values shown are nominal.

[†]This symbol is in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, VCC (see Note	1)	7 V
Input voltage		7 V
Operating free-air temperature:	SN54LS55	-55°C to 125°C
	SN74LS55	0°C to 70°C
Storage temperature range		-65°C to 150°C

NOTE 1: Voltage values are with respect to network ground terminal.

recommended operating conditions

			SN54LS55			SN74LS55			
		MIN	NOM	MAX	MIN	MOM	MAX	UNIT	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V	
VIH	High-level input voltage	2			2			V	
VIL	Low-level input voltage			0.7			0.8	V	
Іон	High-level output current			- 0.4		·	- 0.4	mA	
loL	Low-level output current			4			. 8	mA	
TA	Operating free-air temperature	- 55		125	0		70	°c	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONST		S	SN54LS55			SN74LS55		
	TEST CONDITIONS!			MIN	TYP ‡	MAX	MIN	TYP‡	MAX	UNIT
VIK	V _{CC} = MIN,	$I_1 = -18 \text{ mA}$				1.5			1.5	V
Voн	V _{CC} = MIN,	VIL = MAX,	I _{OH} = - 0.4 mA	2.5	3.4		2.7	3.4		٧
VOL	V _{CC} = MIN,	V _{1H} = 2 V,	10L = 4 mA		0.25	0.4		0.25	0.4	V
VOL	V _{CC} = MIN,	V _{IH} = 2 V,	IOL = 8 mA					0.35	0.5	
l _l	VCC = MAX,	V1 = 7 V				0.1			0.1	mA
ЧН	VCC = MAX,	VI = 2.7 V				20			20	μΑ
li L	VCC = MAX,	VI = 0.4 V				0.4			- 0.4	mA
10s §	VCC = MAX			- 20		- 100	- 20		- 100	mA
ГССН	VCC = MAX,	VI = 0 V			0.4	0.8		0.4	8.0	mA
ICCL	VCC = MAX,	See Note 2			0.7	1.3		0.7	1.3	mA

 $^{^\}dagger$ For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (see note 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
tPLH	Any	Y	$R_L = 2 k\Omega$,	C ₁ = 15 pF		12	20	ns
^t PHL	,y	'	11 - 2 832,	C[- 15 pr		12.5	20	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.



[‡] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ} \text{C}$.

[§]Not more than one output should be shorted at a time, and the duration of the short-circuit should not exceed one second.

NOTE 2: All outputs of one AND gate at 4.5 V, all others at GND.

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